

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended). An integrated circuit package comprising:
 - (a) an integrated circuit die having at least one circuit etched thereon, the circuit comprising elements which require theoretically negative reactive component values; and
 - (b) a housing containing said integrated circuit die, wherein said integrated circuit die is electrically coupled to said housing using at least one wire bond; wherein ~~said each~~ wire bond(s) has ~~(have)~~ an inductance associated therewith; and wherein the negative reactive component values theoretically required by the integrated circuit are actually incorporated into the circuit through the use of wire bonds having pre-determined inductance values. wherein said wire bond inductance is used to facilitate operation of said at least one circuit.
2. (Currently Amended). The integrated circuit of claim 1, wherein the circuit comprises an impedance inverter. A method of providing inductance to facilitate operation of a circuit contained in an integrated circuit package comprising making available wire bond inductance to said circuit.
- 3-13. (Cancelled).